

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客 户 : _____

PRODUCT 产 品 : _____ SAW FILTER

MODEL NO 型 号 : _____ HDF114A W2

PREPARED 编 制 : _____ CHECKED 审 核 : _____

APPROVED 批 准 : _____ D A T E 日 期 : _____ 2006-5-11

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司

Shoulder Electronics Limited

更改历史记录

History Record

[illegible]

1. SCOPE

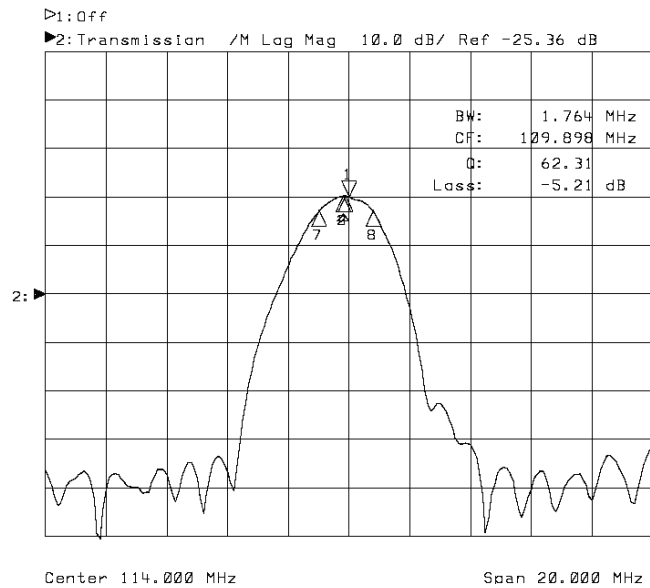
This specification shall cover the characteristics of SAW filter F110A

2. ELECTRICAL SPECIFICATION

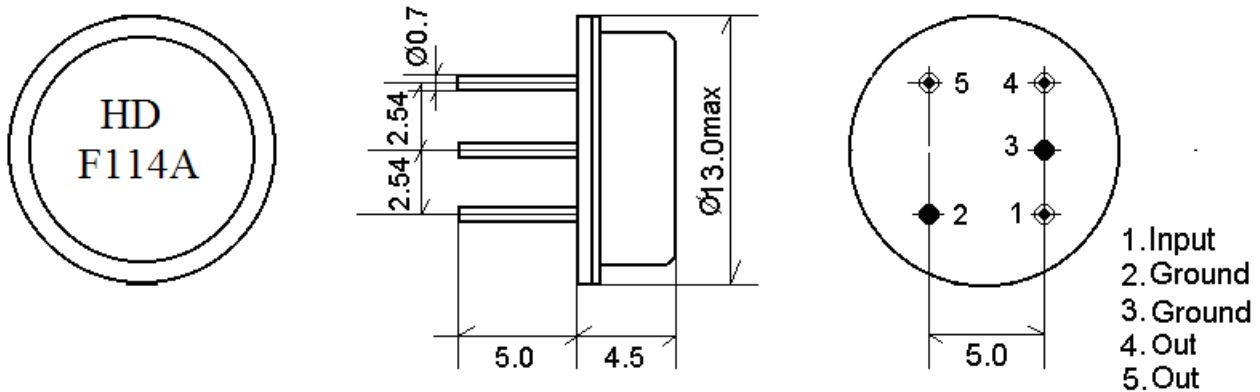
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

2.2 Electronic Characteristics

型号 Part Number	HDF114A
中心频率(fo)(MHz) Nominal Center Frequency	114.0
3dB 带宽 Bandwidth(from fo)(MHz)	1.6 typ.
阻带衰减 Stop Band Attenuation (from peak level)(dB) 1)fo-5.0MHz 2)fo±3.0MHz 3)fo+5.0MHz	40min 30min 40min
插入损耗(dB) Insertion Loss(at minimum loss point)	6.0max
群延时波动(fo+/-576KHz)(μscc.) Group Delay Deviation	0.200
输入/输出阻抗 Input/output Impedance	50Ω//0pF



3. DIMENSION



4. ENVIRONMENTAL CHARACTERISTICS

4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C $\pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

4-5 Solderability

Subject the device terminals into the solder bath at 245°C $\pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.